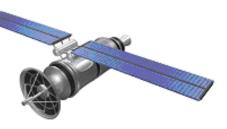
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The Global Semiconductor Industry Analysts

FH MONDAY

1 August 2022

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Chip industry splits over U.S. CHIPS Act benefits for Intel

Several U.S. chip firms are reportedly debating whether to oppose \$52 billion in congressional subsidies for chip fab construction if the final deal disproportionately favors Intel and others. The split in the industry was reported by Reuters, citing two unnamed sources concerned about the advantages that could come to their direct competitors such as Intel.

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Rohde & Schwarz unveils on-wafer device characterization test solution

Rohde & Schwarz now offers a test solution for full radio frequency (RF) performance characterization of the device under test (DUT) on-wafer, which combines the powerful R&S ZNA vector network analyzer (VNA) from Rohde & Schwarz with industry-leading engineering probe systems from FormFactor.

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TALK TO US







SkyWater to Build \$1.8 Billion Fab in Indiana

SkyWater Technology, a U.S. foundry that's a trusted chip supplier for the Department of Defense (DOD), plans to build a \$1.8 billion chip R&D and production facility in the state of Indiana. The fab, which would be located on the campus of Purdue University in the town of West Lafayette, is planned as a public—private partnership that will count on some of the \$52 billion in funding from the proposed CHIPS Act.

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EVENTS

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- September 2022- London UK

Industry Forecast Briefing

- September 2022- London UK

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First Power 'ChiP' Fab Supports Automotive Electrification

Power supplies are instrumental for the success of applications in which high efficiency, reliability, and performance are mandatory requirements. This includes the most recent applications in the automotive sector, where the progressive electrification of the vehicle fleet imposes unprecedented challenges to increase range and reduce charging time, as well as the size and weight of the power delivery network.

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Fujifilm boosts U.S. electronic materials business by \$350M to serve chip industry

The supply chain for electronics production and the materials behind computers and chips has been tested over the past two years and continues to be cited by leading companies as a major concern for investors and customers.

In the meantime, the long-term outlook calls for greater demand for materials, components and chips used in the global supply chain.

Companies such as TSMC, Samsung and Intel have sought to expand production for chips, while the materials themselves have come into focus.

Chip industry splits over U.S. CHIPS Act benefits for Intel

Several U.S. chip firms are reportedly debating whether to oppose \$52 billion in congressional subsidies for chip fab construction if the final deal disproportionately favors Intel and others.

The split in the industry was reported by Reuters, citing two unnamed sources concerned about the advantages that could come to their direct competitors such as Intel.

Fabless chip companies like AMD, Nvidia and Qualcomm that design chips but do not manufacture them would see no direct benefit from subsidies to build plants or tax benefits for production tools. Intel, which wants to build plants in Ohio valued at \$20 billion, and other U.S. companies like Micron and Texas Instruments both design and manufacture chips.

Rohde & Schwarz unveils on-wafer device characterization test solution

Rohde & Schwarz now offers a test solution for full radio frequency (RF) performance characterization of the device under test (DUT) on-wafer, which combines the powerful R&S ZNA vector network analyzer (VNA) from Rohde & Schwarz with industry-leading engineering probe systems from FormFactor. As a result, semiconductor manufacturers can perform reliable and repeatable on-wafer device characterization in the development phase, during product qualification and in production.

5G RF front-end designers aim to ensure proper RF capabilities for frequency coverage and output power while optimizing energy efficiency. An important phase in this process is investigating the RF design, to get feedback on the design as early as possible and assess the performance and capabilities already on the wafer level. Characterizing a DUT in an on-wafer environment requires a measurement system that includes a VNA, a probe station, RF probes, cables or adapters, a dedicated calibration method as well as calibration substrates for the particular DUT or application.

SkyWater to Build \$1.8 Billion Fab in Indiana

SkyWater Technology, a U.S. foundry that's a trusted chip supplier for the Department of Defense (DOD), plans to build a \$1.8 billion chip R&D and production facility in the state of Indiana.

The fab, which would be located on the campus of Purdue University in the town of West Lafayette, is planned as a public–private partnership that will count on some of the \$52 billion in funding from the proposed CHIPS Act.

The investment joins SkyWater, Purdue, and the Indiana government working to obtain federal incentives defined in the CHIPS Act that's currently making its way through Congress.

"This endeavor to bolster our chip fabrication facilities will rely on funding from the CHIPS Act," Thomas Sonderman, SkyWater CEO, said in a prepared statement. "Federal investment will enable SkyWater to more quickly expand our efforts to address the need for strategic reshoring of semiconductor manufacturing."

First Power 'ChiP' Fab Supports Automotive Electrification and Data Centers

Power supplies are instrumental for the success of applications in which high efficiency, reliability, and performance are mandatory requirements. This includes the most recent applications in the automotive sector, where the progressive electrification of the vehicle fleet imposes unprecedented challenges to increase range and reduce charging time, as well as the size and weight of the power delivery network. Data centers, where an enormous amount of data is stored and processed (also thanks to the aid of artificial–intelligence algorithms), require ultra–efficient power solutions capable of operating 24/7 while minimizing power consumption and taking up less space and weight.

Vicor Corporation, the industry leader in innovative power—module design and manufacturing, has recently celebrated the opening of a new 90,000–square—foot, state—of—the—art manufacturing facility in Andover, Massachusetts. The power—module—manufacturing facility, created to support the demand coming from the fast—growing automotive electrification and data center/Al industries, is the world's first converter—housed—in—package (CHiP) fabrication facility. The new ChiP fab sets the standard for scalable, high—volume, cost—effective, and reliable power—module manufacturing in the United States.